


Hybrid circuit boards An alternative that pays off handsomely!

 Modern components often need to combine different characteristics. In most cases, this can be effectively accomplished with hybrid layer structures.

Flex-Rigid

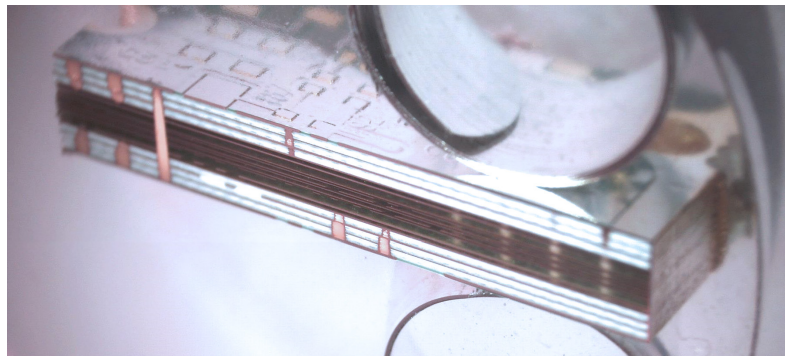
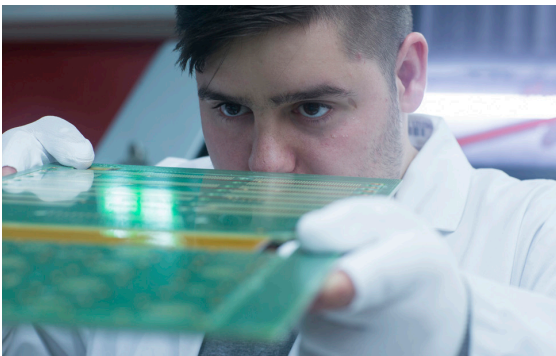
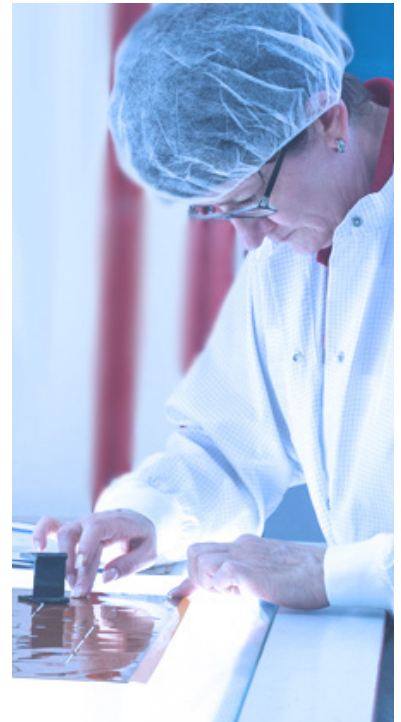
The combination of rigid and flexible base materials allows the full utilisation of reduced construction spaces. On many occasions, the flex-rigid printed circuit board represents a cost-effective alternative to more rigid printed circuit boards, which must be elaborately interconnected otherwise.

RF Hybrid

FR4 meets Ceramic & Teflon. Hybrid structures are recommended for components with varying signal integrity requirements in their different circuit parts. Quite often, combining materials pays off because the cost of high-frequency compatible substrates is higher than FR4 by a double-digit factor.

Special features of the circuit board

By using hybrid structures, circuit board areas exposed to the environment can be conferred specific properties. Common requirements include low outgassing, low moisture absorption, specific expansion properties, or increased thermal conductivity.



XY-Hybrid

Conventional hybrid circuit boards are restricted to the layered (Z-direction) use of different materials. To offer our customers broader development opportunities, we have designed a method whereby we can also change the base materials within a circuit board in the X / Y direction.

Let our know-how convince you:

- 37 years of experience with different material combinations.
- Proven skills in processing of materials with different expansion coefficients.
- Bonding of Teflon-based substrates.
- Production of high-quality metallisation in varying material combinations.